

VIA AND VIA LANDING STRUCTURES FOR SMOOTHING TRANSITIONS IN
MULTI-LAYER SUBSTRATES

ABSTRACT OF THE DISCLOSURE

5 An integrated circuit arrangement or package includes
a set of contact pads arranged in a pattern and a multi-
layer conductive structure, which electrically connects the
set of contact pads to at least one signal line. The
conductive structure provides impedance matching between
10 the pads and the at least one signal line.